

Title (en)
CONNECTING DEVICE

Title (de)
VERBINDUNGSEINRICHTUNG

Title (fr)
DISPOSITIF DE CONNEXION

Publication
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Application
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Abstract (en)
[origin: WO0227789A1] The aim of the invention is to take up the smallest amount of space possible while effecting the thermomechanical release in tension at the junction between a circuit unit (2) and contact device (4) of a circuit (1), said junction being provided by means of the connecting device (10). To this end, the connecting device (10) is essentially provided as a prefabricated metallic or alloy region in the area of the circuit unit (2) and in the area of the contact device (4) while avoiding, to the greatest possible extent, the use of adhesive elements and solder elements.

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